09719844

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NEWS 1		Web Page URLs for STN Seminar Schedule - N. America
NEWS 2	Jan 25	BLAST(R) searching in REGISTRY available in STN on the Web
NEWS 3	Jan 29	FSTA has been reloaded and moves to weekly updates
NEWS 4	Feb 01	DKILIT now produced by FIZ Karlsruhe and has a new update frequency
NEWS 5	Feb 19	Access via Tymnet and SprintNet Eliminated Effective 3/31/02
NEWS 6	Mar 08	Gene Names now available in BIOSIS
NEWS 7	Mar 22	TOXLIT no longer available
NEWS 8	Mar 22	TRCTHERMO no longer available
NEWS 9	Mar 28	US Provisional Priorities searched with P in CA/CAplus and USPATFULL
NEWS 10	Mar 28	LIPINSKI/CALC added for property searching in REGISTRY
NEWS 11	Apr 02	PAPERCHEM no longer available on STN. Use PAPERCHEM2 instead.
NEWS 12	Apr 08	"Ask CAS" for self-help around the clock
NEWS 13	Apr 09	BEILSTEIN: Reload and Implementation of a New Subject Area
NEWS 14	Apr 09	ZDB will be removed from STN
NEWS 15	Apr 19	US Patent Applications available in IFICDB, IFIPAT, and IFIUDB
NEWS 16	Apr 22	Records from IP.com available in CAPLUS, HCAPLUS, and ZCAPLUS
NEWS 17	Apr 22	BIOSIS Gene Names now available in TOXCENTER
NEWS 18	Apr 22	Federal Research in Progress (FEDRIP) now available

NEWS EXPRESS	February 1 CURRENT WINDOWS VERSION IS V6.0d, CURRENT MACINTOSH VERSION IS V6.0a(ENG) AND V6.0Ja(JP), AND CURRENT DISCOVER FILE IS DATED 05 FEBRUARY 2002
NEWS HOURS	STN Operating Hours Plus Help Desk Availability
NEWS INTER	General Internet Information
NEWS LOGIN	Welcome Banner and News Items
NEWS PHONE	Direct Dial and Telecommunication Network Access to STN
NEWS WWW	CAS World Wide Web Site (general information)

Enter NEWS followed by the item number or name to see news on that specific topic.

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* * * * * * * * * * * * * STN Columbus * * * * * * * * * * * * * * * *

FILE 'HOME' ENTERED AT 18:21:27 ON 13 MAY 2002

=> file registry

COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	0.21	0.21

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FILE 'REGISTRY' ENTERED AT 18:22:06 ON 13 MAY 2002
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STRUCTURE FILE UPDATES: 12 MAY 2002 HIGHEST RN 414856-11-4
DICTIONARY FILE UPDATES: 12 MAY 2002 HIGHEST RN 414856-11-4

TSCA INFORMATION NOW CURRENT THROUGH July 7, 2001

Please note that search-term pricing does apply when
conducting SmartSELECT searches.

Crossover limits have been increased. See HELP CROSSOVER for details.

Calculated physical property data is now available. See HELP PROPERTIES
for more information. See STNote 27, Searching Properties in the CAS
Registry File, for complete details:
http://www.cas.org/ONLINE/STN/STNOTES/stnotes27.pdf

=>
Uploading 09543628.str

L1 STRUCTURE UPLOADED

=> s full l1
FULL SEARCH INITIATED 18:22:23 FILE 'REGISTRY'
FULL SCREEN SEARCH COMPLETED - 1126 TO ITERATE

100.0% PROCESSED 1126 ITERATIONS 815 ANSWERS
SEARCH TIME: 00.00.01

L2 815 SEA SSS FUL L1

=> file caplus
COST IN U.S. DOLLARS

	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	140.28	140.49

FILE 'CAPLUS' ENTERED AT 18:22:31 ON 13 MAY 2002
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FILE COVERS 1907 - 13 May 2002 VOL 136 ISS 20
FILE LAST UPDATED: 10 May 2002 (20020510/ED)

This file contains CAS Registry Numbers for easy and accurate
substance identification.

09719844

CAS roles have been modified effective December 16, 2001. Please check your SDI profiles to see if they need to be revised. For information on CAS roles, enter HELP ROLES at an arrow prompt or use the CAS Roles thesaurus (/RL field) in this file.

```
=> s electronic and l2
        363585 ELECTRONIC
         21498 ELECTRONICS
        378840 ELECTRONIC
                  (ELECTRONIC OR ELECTRONICS)
          1391 L2
L3          56 ELECTRONIC AND L2

=> s l3 and (adhesive or adhesion)
        141668 ADHESIVE
         92659 ADHESIVES
        160378 ADHESIVE
                  (ADHESIVE OR ADHESIVES)
        200551 ADHESION
          2593 ADHESIONS
        201407 ADHESION
                  (ADHESION OR ADHESIONS)
L4          11 L3 AND (ADHESIVE OR ADHESION)

=> d ibib abs hitstr 1

L4   ANSWER 1 OF 11  CAPLUS  COPYRIGHT 2002 ACS
ACCESSION NUMBER:        2001:692309  CAPLUS
DOCUMENT NUMBER:         135:243394
TITLE:                   Die-attaching polyurethane acrylate adhesive
                         paste compositions with fast-curing character for
                         semiconductor devices
INVENTOR(S):             Kagimoto, Yoshihiro
PATENT ASSIGNEE(S):      Sumitomo Bakelite Co., Ltd., Japan
SOURCE:                  Jpn. Kokai Tokkyo Koho, 7 pp.
                         CODEN: JKXXAF
DOCUMENT TYPE:           Patent
LANGUAGE:                Japanese
FAMILY ACC. NUM. COUNT:  1
PATENT INFORMATION:

     PATENT NO.          KIND  DATE           APPLICATION NO.  DATE
     ------------------  ----  --------       ---------------  --------
     JP 2001257220        A2   20010921       JP 2000-68099    20000313
AB   Title compn. comprises (A) urethane di(meth)acrylate derived from
     polyalkylene glycol, diisocyanate, and hydroxyalkyl (meth)acrylic acid,
     (B) (meth)acryl group-contg. reactive diluent, (C) triglycidyl
     isocyanurate, (D) phosphoric acid group-contg. (meth)acrylate, (E) epoxy
     alkoxysilane, (F) org. peroxide and/or azo compd., (G) inorg. filler,
     wherein the wt. ratio of F/(A + B + C) = 0.1-5%.  Thus, a compn.
     comprising Aronix M-1600 45, diethylene glycol monoacrylate Ph ether 45,
     T.E.P.I.C. 10, cumyl peroxyneodecanoate 0.5, Kayamer PM 21 1, KMB 303 0.5,
     and powd. Ag 300 parts was kneaded to give a conductive paste exhibiting
     good stability, workability, and fast curing property.
IT   360796-01-6P 360796-02-7P 360796-03-8P
     RL: IMF (Industrial manufacture); POF (Polymer in formulation); PRP
     (Properties); TEM (Technical or engineered material use); PREP
     (Preparation); USES (Uses)
        (manuf. of polyurethane acrylate die-attaching adhesive paste
        with fast-curing character for semiconductor devices)
RN   360796-01-6  CAPLUS
CN   Hexanoic acid, 6-hydroxy-, 2-[(2-methyl-1-oxo-2-propenyl)oxy]ethyl ester,
```

phosphate, polymer with Aronix M 1600, 2-(2-phenoxyethoxy)ethyl 2-propenoate, trimethoxy[2-(7-oxabicyclo[4.1.0]hept-3-yl)ethyl]silane and 1,3,5-tris(oxiranylmethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

CM 1

CRN 100629-45-6
CMF Unspecified
CCI MAN

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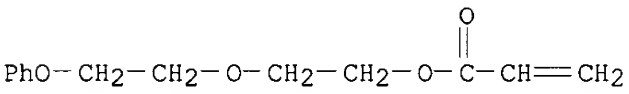
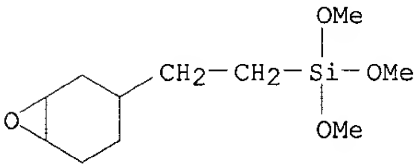
CM 2

CRN 61630-25-9
CMF C13 H16 O4



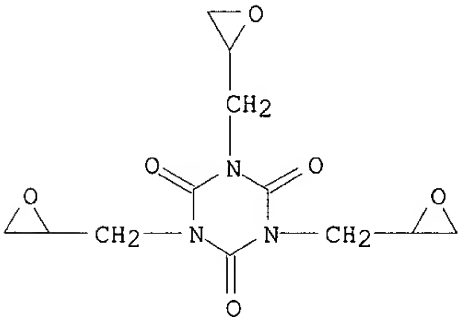
CM 3

CRN 3388-04-3
CMF C11 H22 O4 Si



CM 4

CRN 2451-62-9
CMF C12 H15 N3 O6

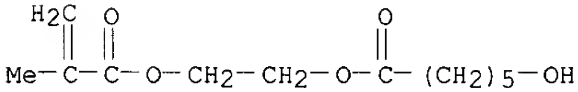


CM 5

CRN 103370-83-8
CMF C12 H20 O5 . x H3 O4 P
CDES 8:GD,ESTER

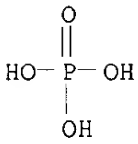
CM 6

CRN 85099-10-1
CMF C12 H20 O5



CM 7

CRN 7664-38-2
CMF H3 O4 P



RN 360796-02-7 CAPLUS
CN Hexanoic acid, 6-hydroxy-, 2-[(2-methyl-1-oxo-2-propenyl)oxy]ethyl ester, phosphate, polymer with Aronix M 1600, 2-([1,1'-biphenyl]-4-yloxy)ethyl 2-propenoate, trimethoxy[2-(7-oxabicyclo[4.1.0]hept-3-yl)ethyl]silane and 1,3,5-tris(oxiranylmethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

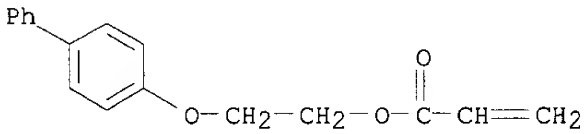
CM 1

CRN 100629-45-6
CMF Unspecified
CCI MAN

*** STRUCTURE DIAGRAM IS NOT AVAILABLE ***

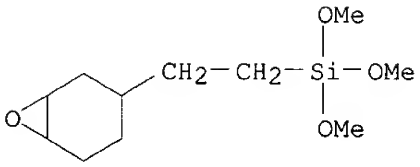
CM 2

CRN 73586-34-2
CMF C17 H16 O3



CM 3

CRN 3388-04-3
CMF C11 H22 O4 Si



CM 4

CRN 2451-62-9
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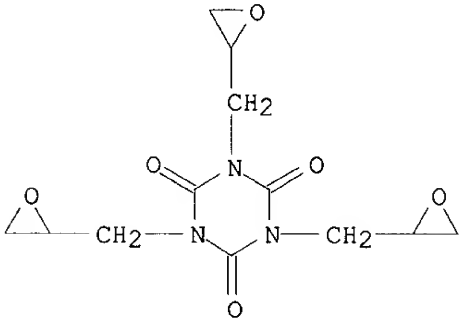
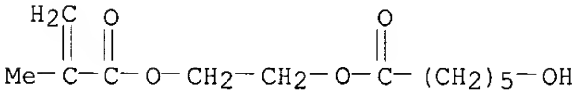


CM 5

CRN 103370-83-8
CMF C12 H20 O5 . x H3 O4 P
CDES 8:GD,ESTER

CM 6

CRN 85099-10-1
CMF C12 H20 O5



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CRN 7664-38-2
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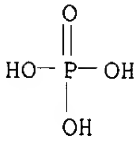

RN 360796-03-8 CAPLUS
CN Hexanoic acid, 6-hydroxy-, 2-[(2-methyl-1-oxo-2-propenyl)oxy]ethyl ester, phosphate, polymer with Aronix M 1600, (octahydro-4,7-methano-1H-indene-5,?-diyl)bis(methylene) di-2-propenoate, trimethoxy[2-(7-oxabicyclo[4.1.0]hept-3-yl)ethyl]silane and 1,3,5-tris(oxiranylmethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

CM 1

CRN 100629-45-6
CMF Unspecified
CCI MAN

*** STRUCTURE DIAGRAM IS NOT AVAILABLE ***

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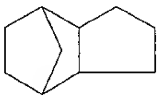
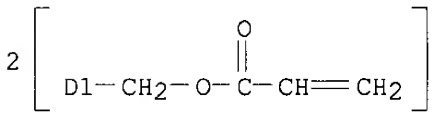
CRN 42594-17-2
CMF C18 H24 O4
CCI IDS
CDES *





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CRN 3388-04-3
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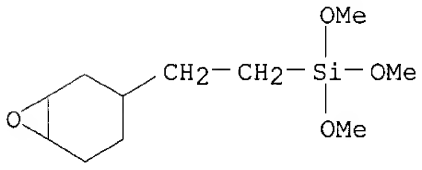
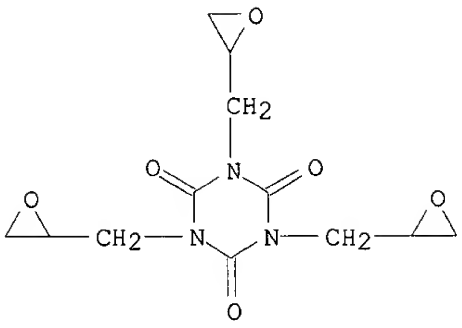


CM 4

CRN 2451-62-9
CMF C12 H15 N3 O6

09719844



CM 5

CRN 103370-83-8
CMF C12 H20 O5 . x H3 O4 P
CDES 8:GD,ESTER

CM 6

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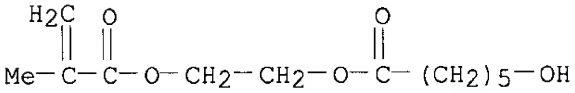
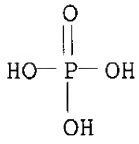
CMF C12 H20 O5



CM 7

CRN 7664-38-2
CMF H3 O4 P



=> d ibib abs hitstr 2

L4 ANSWER 2 OF 11 CAPLUS COPYRIGHT 2002 ACS
ACCESSION NUMBER: 2000:268555 CAPLUS
DOCUMENT NUMBER: 132:309393
TITLE: Curable compositions and **adhesive** compositions for manufacture of circuit parts and printed circuit boards
INVENTOR(S): Tong, Quinn K.; Ma, Bodan; Xiao, Chaodong
PATENT ASSIGNEE(S): National Starch and Chemical Investment Holding Corp., USA
SOURCE: Jpn. Kokai Tokkyo Koho, 111 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese

09719844

FAMILY ACC. NUM. COUNT: 2
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2000119335	A2	20000425	JP 1999-188845	19990702
US 6281314	B1	20010828	US 1999-336324	19990618
CN 1245181	A	20000223	CN 1999-119203	19990630
KR 2000011442	A	20000225	KR 1999-26615	19990702

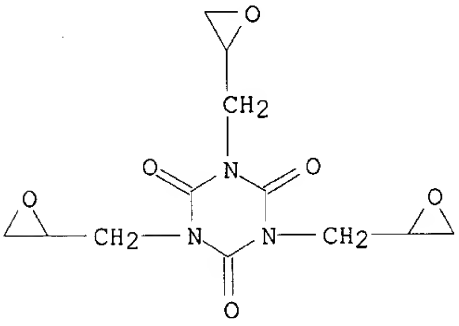
PRIORITY APPLN. INFO.: US 1998-91490P P 19980702
US 1999-336324 A 19990618

AB Title curable compns. contain (A) maleimides and (B) curing initiators consisting of free-radical initiators and/or photopolymn. initiators. Title **adhesive** compns. contain (C) vinyl compds. and B. Markush structures of A and C are given in the document. Thus, a compn. contg. Versalink P 650 (bismaleimide), cyclohexanedimethanol divinyl ether, and Irgacure 651 (.alpha.,.alpha.-dimethoxy-.alpha.-phenylacetophenone) was irradiated with UV light to bond a Si die.

IT **2451-62-9**, Tris(epoxypropyl) isocyanurate
RL: RCT (Reactant); RACT (Reactant or reagent)
(maleimide-contg. photocurable **adhesive** compns. for manuf. of printed circuit boards)

RN 2451-62-9 CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)- (9CI) (CA INDEX NAME)



=> d ibib abs hitstr 3

L4 ANSWER 3 OF 11 CAPLUS COPYRIGHT 2002 ACS
ACCESSION NUMBER: 2000:12715 CAPLUS
DOCUMENT NUMBER: 132:79493
TITLE: Die attach **adhesives** for use in microelectronics
INVENTOR(S): Herr, Donald; Schultz, Rose Ann; Xu, Ping Yong
PATENT ASSIGNEE(S): National Starch and Chemical Investment Holding Corp., USA
SOURCE: Eur. Pat. Appl., 44 pp.
CODEN: EPXXDW
DOCUMENT TYPE: Patent
LANGUAGE: English
FAMILY ACC. NUM. COUNT: 3
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
EP 969065	A2	20000105	EP 1999-112734	19990701

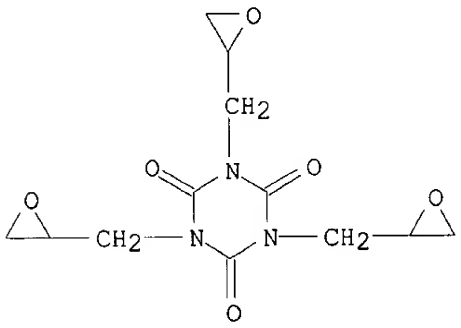
EP 969065	A3	20000223			
R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO					
US 6265530	B1	20010724	US 1999-336245	19990618	
CN 1248603	A	20000329	CN 1999-111395	19990630	
JP 2000044888	A2	20000215	JP 1999-189198	19990702	
KR 2000011449	A	20000225	KR 1999-26638	19990702	
US 2002007042	A1	20020117	US 2001-773800	20010201	
PRIORITY APPLN. INFO.:			US 1998-91492P	P	19980702
			US 1999-336245	A	19990618

AB A curable **adhesive** compn. for use in bonding an **electronic** component to a substrate comprises a maleimide compd. and a curing initiator selected from the group consisting of a free-radical initiator, a photoinitiator, and a combination of those.

IT **2451-62-9**, Tris(epoxypropyl)isocyanurate
RL: RCT (Reactant); RACT (Reactant or reagent)
(die attach **adhesives** for use in microelectronics)

RN 2451-62-9 CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)- (9CI) (CA INDEX NAME)



REFERENCE COUNT: 1 THERE ARE 1 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

=> d ibib abs hitstr 4

L4 ANSWER 4 OF 11 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER:	2000:12713 CAPLUS
DOCUMENT NUMBER:	132:79491
TITLE:	Package encapsulant compositions for use in **electronic** devices
INVENTOR(S):	Ma, Bodan; Tong, Quinn K.
PATENT ASSIGNEE(S):	National Starch and Chemical Investment Holding Corporation, USA
SOURCE:	Eur. Pat. Appl., 45 pp. CODEN: EPXXDW
DOCUMENT TYPE:	Patent
LANGUAGE:	English
FAMILY ACC. NUM. COUNT:	1
PATENT INFORMATION:	

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
EP 969063	A2	20000105	EP 1999-112725	19990701
EP 969063	A3	20000223		
R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO				

US 6316566	B1	20011113	US 1999-336246	19990618
CN 1244562	A	20000216	CN 1999-119202	19990630
KR 2000011447	A	20000225	KR 1999-26624	19990702
JP 2000103817	A2	20000411	JP 1999-189376	19990702
US 2001056162	A1	20011227	US 2001-894540	20010628

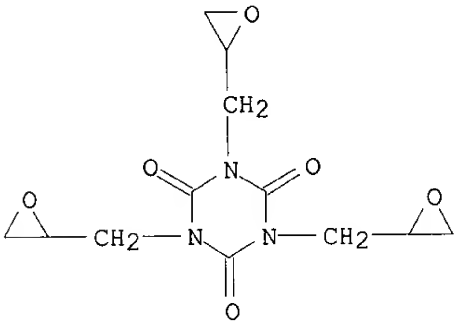
PRIORITY APPLN. INFO.: US 1998-91493P P 19980702
US 1999-336246 A 19990618

AB A curable package encapsulant compn. comprises a maleimide compd. and a curing initiator selected from the group consisting of a free-radical initiator, a photoinitiator, and a combination of those.

IT **2451-62-9**, Tris(epoxypropyl)isocyanurate
RL: RCT (Reactant); RACT (Reactant or reagent)
(package encapsulant compns. for use in **electronic** devices)

RN 2451-62-9 CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)- (9CI) (CA INDEX NAME)



REFERENCE COUNT: 1 THERE ARE 1 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

=> d ibib abs hitstr 5

L4 ANSWER 5 OF 11 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 2000:12712 CAPLUS
DOCUMENT NUMBER: 132:79440
TITLE: Method of making **electronic** components using reworkable **adhesives**
INVENTOR(S): Tong, Quinn K.; Ma, Bodan; Xiao, Chaodong; Shenfield, David
PATENT ASSIGNEE(S): National Starch and Chemical Investment Holding Corporation, USA
SOURCE: Eur. Pat. Appl., 44 pp.
CODEN: EPXXDW
DOCUMENT TYPE: Patent
LANGUAGE: English
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
EP 969062	A2	20000105	EP 1999-112724	19990701
EP 969062	A3	20000223		
R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO				
CN 1243141	A	20000202	CN 1999-111479	19990630
JP 2000086978	A2	20000328	JP 1999-189698	19990702

PRIORITY APPLN. INFO.: US 1998-91506P P 19980702

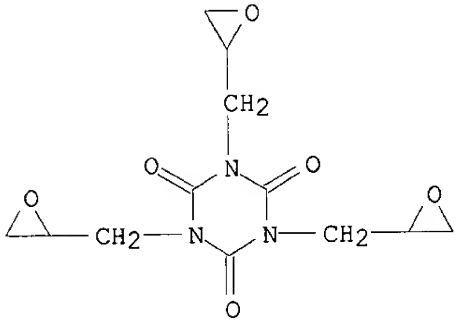
US 1999-335809 A 19990618

AB A method for making an **electronic** component adhered to a substrate with a cured reworkable **adhesive** compn. comprises: (a) providing a curable reworkable **adhesive** compn. comprising (i) one or more mono-functional vinyl compds. in a major amt. effective to provide thermoplastic properties, and (ii) optionally, one or more polyfunctional vinyl compds. in a minor amt. ineffective to diminish the thermoplastic properties of the cured compn., (iii) a curing initiator selected from the group consisting of a radical initiator, a photoinitiator, and a combination of those, (iv) optionally, one or more fillers; (v) optionally, one or more **adhesion** promoters; (b) applying the curable reworkable **adhesive** compn. to either the **electronic** component or the substrate (c) contacting the **electronic** component and the substrate together; and (d) curing the compn. in situ.

IT **2451-62-9**, Tris(epoxypropyl)isocyanurate
RL: RCT (Reactant); RACT (Reactant or reagent)
(method of making **electronic** components using reworkable **adhesives**)

RN 2451-62-9 CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)- (9CI) (CA INDEX NAME)



REFERENCE COUNT: 1 THERE ARE 1 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

=> d ibib abs hitstr 6

L4 ANSWER 6 OF 11 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 2000:12708 CAPLUS
DOCUMENT NUMBER: 132:79488
TITLE: Method of making encapsulated **electronic** component with reworkable package encapsulants
INVENTOR(S): Ma, Bodan; Tong, Quinn K.; Xiao, Chaodong
PATENT ASSIGNEE(S): National Starch and Chemical Investment Holding Corporation, USA
SOURCE: Eur. Pat. Appl., 30 pp.
CODEN: EPXXDW
DOCUMENT TYPE: Patent
LANGUAGE: English
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
EP 969058	A2	20000105	EP 1999-112719	19990701
EP 969058	A3	20000223		

R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO

CN 1254182	A	20000524	CN 1999-111271	19990630
KR 2000011414	A	20000225	KR 1999-26329	19990701
JP 2000036505	A2	20000202	JP 1999-189331	19990702

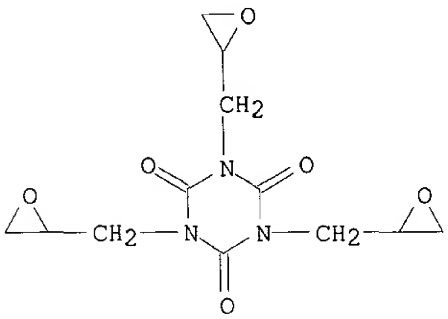
PRIORITY APPLN. INFO.: US 1998-109189 A 19980702

AB Encapsulated **electronic** components are manufd. by using reworkable encapsulants prepd. from in-situ-curable compns. contg. mono- and(or) polyfunctional maleimide compds. or mono- and(or) polyfunctional vinyl compds. other than maleimide compds. or a combination of the maleimide and vinyl compds., a curing initiator, and, optionally, or .gtoreq.1 filler or **adhesion** promoter. A typical encapsulant compn. contained Versalink P-650 (bismaleimide prepd. from polytetramethylene glycol di-p-aminobenzoate) 1.01, cyclohexanedimethanol divinyl ether 0.19, Irgacure 651 0.06, and hydrophilic fused silica 3.78 g.

IT **2451-62-9**, Triglycidyl isocyanurate
RL: RCT (Reactant); RACT (Reactant or reagent)
(encapsulant component precursor; making encapsulated **electronic** components with reworkable package encapsulants from compns. contg. maleimide and vinyl compds.)

RN 2451-62-9 CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)- (9CI) (CA INDEX NAME)



REFERENCE COUNT: 1 THERE ARE 1 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

=> d ibib abs hitstr 7

L4 ANSWER 7 OF 11 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 1999:788216 CAPLUS
DOCUMENT NUMBER: 132:36659
TITLE: Epoxy resin compositions with excellent mold releasability and optical semiconductor devices sealed therewith
INVENTOR(S): Tsuchida, Satoru; Kosaka, Masahiko
PATENT ASSIGNEE(S): Hitachi Chemical Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE

JP 11343395 A2 19991214 JP 1998-152899 19980602

AB The compns. contain epoxy resins and MeCH2(CH2CH2)mCH2CO(OCH2CH2)nOH (I; m = 5-30; n = 2-40; n/m = 0.1-3). Thus, a compn. contg. Epomik R 366 (bisphenol A epoxy resin) 80, TEPIC-S (multifunctional epoxy resin) 20, Rikacid TH (tetrahydrophthalic anhydride) 38, and I (m = 15, n = 10) 1.5 parts was transfer molded and cured to give a test piece showing light transmittance 90% at 600 nm and good **adhesion** to an Al foil and mold releasability after 20 shots.

IT **209804-91-1P**

RL: IMF (Industrial manufacture); POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(epoxy resin compns. with good mold releasability and **adhesion** to metals for sealing optical semiconductor devices)

RN 209804-91-1 CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with Epomik R 366 and 3a,4,7,7a-tetrahydro-1,3-isobenzofurandione (9CI) (CA INDEX NAME)

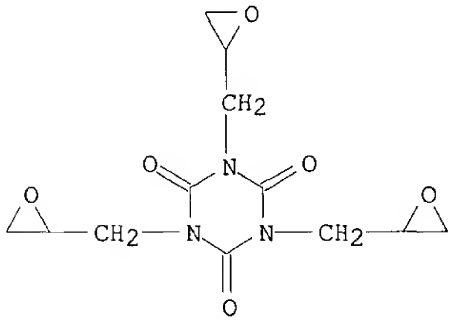
CM 1

CRN 143550-01-0
CMF Unspecified
CCI PMS, MAN

*** STRUCTURE DIAGRAM IS NOT AVAILABLE ***

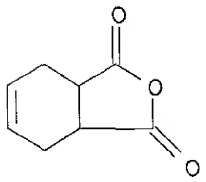
CM 2

CRN 2451-62-9
CMF C12 H15 N3 O6



CM 3

CRN 85-43-8
CMF C8 H8 O3



=> d ibib abs hitstr 8

L4 ANSWER 8 OF 11 CAPLUS COPYRIGHT 2002 ACS
ACCESSION NUMBER: 1999:731776 CAPLUS
DOCUMENT NUMBER: 131:352273
TITLE: Epoxy resin compositions containing polyether-modified silicone oils for packaging photosemiconductor devices
INVENTOR(S): Tsuchida, Satoru; Osaka, Masahiko
PATENT ASSIGNEE(S): Htiachi Chemical Company, Ltd., Japan
SOURCE: U.S., 7 pp.
CODEN: USXXAM
DOCUMENT TYPE: Patent
LANGUAGE: English
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
US 5985954	A	19991116	US 1997-985208	19971202

AB The compn. having good releasability **adhesion** to metals and light transmittance, comprises (A) an epoxy resin [e.g., Epomik R 366 (bisphenol A epoxy resin) and Tepic-S (triglycidyl isocyanurate homopolymer)], (B) a curing agent [Rikacid TH (tetrahydrophthalic anhydride)] and (C) a polyether-modified silicone oil (CH3)3SiO[SiO(CH3)2]m{SiO(CH3)[C3H6O(C2H4O)a(C3H6O)bR]}nSi(CH3)3 (m, n, a .gtoreq.1; b .gtoreq.0; R = H, C1-6 alkyl) having wt. av. mol. wt. 1,000-100,000, silicone unit content {[(m+n+2)/(m+n+2+a+b+1)].times.100} 10-60% and polyether unit content {[(a+b+1)/(m+n+2+a+b+1)].times.100} 40-90%.

IT **209804-91-1P**
RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(epoxy resin compns. contg. polyoxyakylene-modified silicone oils for packaging photosemiconductor devices)

RN 209804-91-1 CAPLUS
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with Epomik R 366 and 3a,4,7,7a-tetrahydro-1,3-isobenzofurandione (9CI) (CA INDEX NAME)

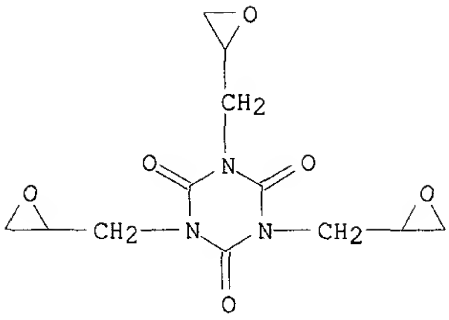
CM 1

CRN 143550-01-0
CMF Unspecified
CCI PMS, MAN

*** STRUCTURE DIAGRAM IS NOT AVAILABLE ***

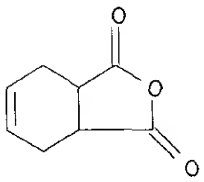
CM 2

CRN 2451-62-9
CMF C12 H15 N3 O6



CM 3

CRN 85-43-8
CMF C8 H8 O3



REFERENCE COUNT: 1 THERE ARE 1 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

=> d ibib abs hitstr 9

L4 ANSWER 9 OF 11 CAPLUS COPYRIGHT 2002 ACS
ACCESSION NUMBER: 1999:699200 CAPLUS
DOCUMENT NUMBER: 131:323593
TITLE: Epoxy resin compositions having good mold release properties and **adhesion** for packaging optical semiconductor devices
INVENTOR(S): Noro, Masato; Komada, Shigeya; Shimata, Katsumi; Okuda, Satoru; Uenishi, Shinjiro; Hattori, Kuniharu
PATENT ASSIGNEE(S): Nitto Denko Corp., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 11 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 11302499	A2	19991102	JP 1998-112589	19980423
US 6221510	B1	20010424	US 1999-295443	19990421
DE 19918580	A1	19991028	DE 1999-19918580	19990423

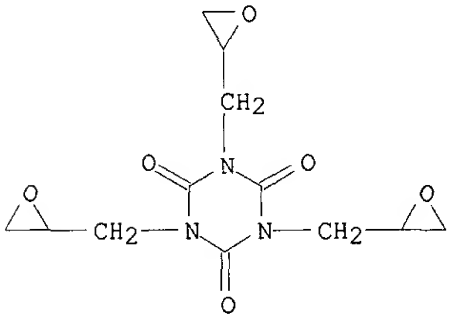
PRIORITY APPLN. INFO.: JP 1998-112589 A 19980423

AB The compn. comprises (A) an epoxy resin (e.g., bisphenol A epoxy resin and triglycidyl isocyanurate), (B) a curing agent (e.g., hexahydrophthalic anhydride), (C) a silane coupling agent having epoxy, mercapto or amino group (e.g., .gamma.-glycidoxypropyltrimethoxysilane), and (D) a release agent having -(CH2CH2)m- and -(CH2CH2O)n- group (m = 8-100 and n = integer; e.g., polyoxyethylene monopentacontyl ether).

IT **146189-72-2P**
RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(epoxy resin compns. having good mold release properties and **adhesion** for packaging optical semiconductor devices)
RN 146189-72-2 CAPLUS
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with (chloromethyl)oxirane, hexahydro-1,3-isobenzofurandione and 4,4'-(1-methylethylidene)bis[phenol] (9CI) (CA INDEX NAME)

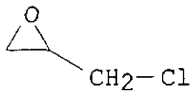
CM 1

CRN 2451-62-9
CMF C12 H15 N3 O6



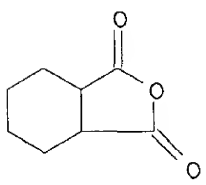
CM 2

CRN 106-89-8
CMF C3 H5 Cl O



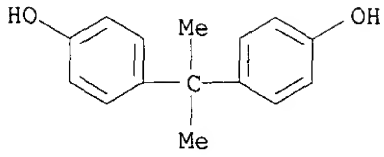
CM 3

CRN 85-42-7
CMF C8 H10 O3



CM 4

CRN 80-05-7
CMF C15 H16 O2



=> d ibib abs hitstr 10

L4 ANSWER 10 OF 11 CAPLUS COPYRIGHT 2002 ACS
ACCESSION NUMBER: 1995:183959 CAPLUS
DOCUMENT NUMBER: 122:134952
TITLE: One-component epoxy resin compositions
INVENTOR(S): Ikeda, Hisao; Gunji, Yasuhiro
PATENT ASSIGNEE(S): Nissan Chemical Ind Ltd, Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 06192396	A2	19940712	JP 1992-346351	19921225

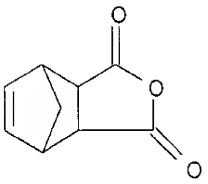
AB Compns. with good heat resistance, dielec. properties, and storage stability at room temp., useful for **adhesives**, laminates, etc., of **electronic** parts, comprise (A) 100 parts low-m.p. isomers found in tris(2,3-epoxypropyl) isocyanurate (I) with m.p. 98-107.degree. and epoxy equiv. wt. .ltoreq.105, (B) 10-150 parts bisphenol epoxy resins liq. at room temp., (C) 0.7-1.1 equiv (vs. total epoxy groups) liq. polycarboxylic acid anhydrides, and (D) 0.1-5% (on total epoxy) acetylacetone complex of Co or Al. Thus, I fraction (m.p. 98-107.degree., epoxy equiv. wt. 100) 50, Epikote 828 50, methylhimic anhydride 122, and Co tris(acetylacetonate) 0.4 part were mixed to obtain a compn. showing storage stability >90 days at 23.degree., which was heated to give cured products showing glass-transition temp. 231.degree. and vol. resistivity at 23.degree. 80 .times. 1015 .OMEGA.-cm.

IT **146189-70-0P 161220-61-7P**
RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(epoxy resin one-component compns. with good heat resistance and storage stability and elec. properties)

RN 146189-70-0 CAPLUS
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with (chloromethyl)oxirane, 4,4'-(1-methylethylidene)bis[phenol] and (3a.alpha.,4.beta.,7.beta.,7a.alpha.)-3a,4,7,7a-tetrahydromethyl-4,7-methanoisobenzofuran-1,3-dione (9CI) (CA INDEX NAME)

CM 1

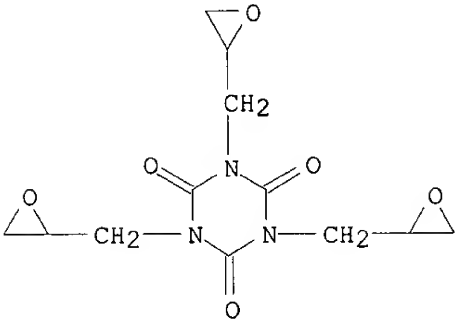
CRN 53584-57-9
CMF C10 H10 O3
CCI IDS
CDES *



D1—Me

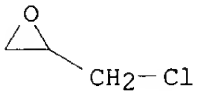
CM 2

CRN 2451-62-9
CMF C12 H15 N3 O6



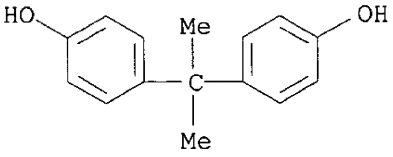
CM 3

CRN 106-89-8
CMF C3 H5 Cl O



CM 4

CRN 80-05-7
CMF C15 H16 O2

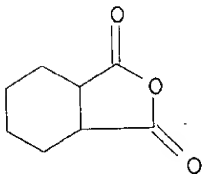


RN 161220-61-7 CAPLUS
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with (chloromethyl)oxirane, hexahydromethyl-1,3-isobenzofurandione and 4,4'-(1-methylethylidene)bis[phenol] (9CI) (CA INDEX NAME)

09719844

CM 1

CRN 25550-51-0
CMF C9 H12 O3
CCI IDS
CDES 8:ID



D1—Me

CM 2

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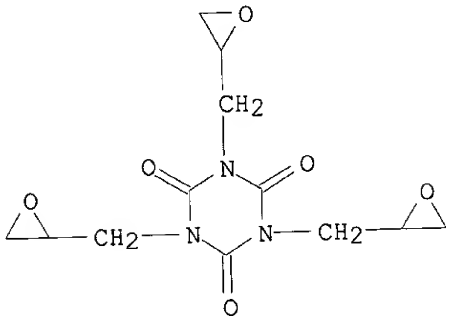
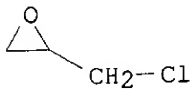


CM 3

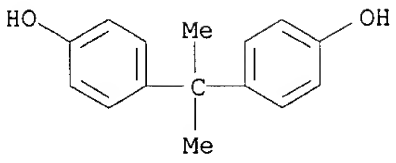
CRN 106-89-8
CMF C3 H5 Cl O



CM 4

CRN 80-05-7
CMF C15 H16 O2

09719844



=> d ibib abs hitstr 11

L4 ANSWER 11 OF 11 CAPLUS COPYRIGHT 2002 ACS
ACCESSION NUMBER: 1990:553934 CAPLUS
DOCUMENT NUMBER: 113:153934
TITLE: Cured glycidyl isocyanurate resins transparent to UV
INVENTOR(S): Sagami, Yosuke; Inagaki, Akihiro; Kajiwara, Yozo; Yoshigahara, Haruyuki
PATENT ASSIGNEE(S): Hysol Japan, Ltd., Japan
SOURCE: Eur. Pat. Appl., 8 pp.
CODEN: EPXXDW
DOCUMENT TYPE: Patent
LANGUAGE: English
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
EP 355728	A2	19900228	EP 1989-115239	19890818
EP 355728	A3	19901219		
R: AT, BE, CH, DE, ES, FR, GB, GR, IT, LI, LU, NL, SE				
JP 02187421	A2	19900723	JP 1989-210175	19890816

PRIORITY APPLN. INFO.: JP 1988-205786 19880819

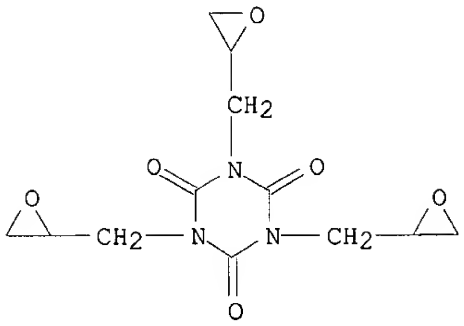
AB The title resins have good strength, toughness, and moisture resistance, and are useful for sealing UV-sensitive **electronic** devices or as transparent substrates, coatings, inks, **adhesives**, or lenses (no data). Thus, a UV-sensitive 64K erasable programmable read-only memory (EPROM) was dip-coated with a compn. of triglycidyl isocyanurate, hexahydrophthalic anhydride, and BuOH, dried, baked at 150.degree., and postcured at 50.degree. to give a device which showed no loss of data or UV erasability after 1000 h at 85.degree. and 85% humidity or 800 thermal cycles between -40.degree. and +80.degree..

IT **28825-96-9P**, Triglycidyl isocyanurate homopolymer
57602-00-3P 129825-75-8P 129825-76-9P
129825-77-0P
RL: PREP (Preparation)
(UV-transparent, manuf. of)

RN 28825-96-9 CAPLUS
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, homopolymer (9CI) (CA INDEX NAME)

CM 1

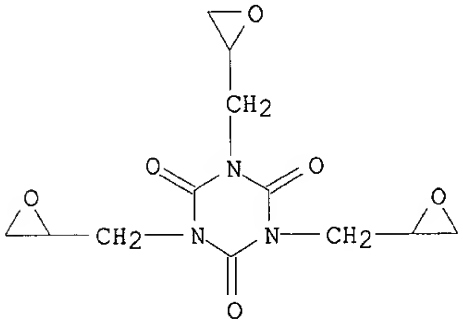
CRN 2451-62-9
CMF C12 H15 N3 O6



RN 57602-00-3 CAPLUS
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with hexahydro-1,3-isobenzofurandione (9CI) (CA INDEX NAME)

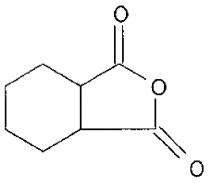
CM 1

CRN 2451-62-9
CMF C12 H15 N3 O6



CM 2

CRN 85-42-7
CMF C8 H10 O3



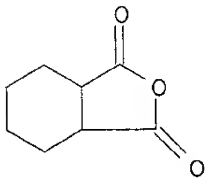
RN 129825-75-8 CAPLUS
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with hexahydromethyl-1,3-isobenzofurandione and 2,2'-[(1-methylethylidene)bis(4,1-cyclohexanediyloxymethylene)]bis[oxirane] (9CI) (CA INDEX NAME)

CM 1

CRN 25550-51-0
CMF C9 H12 O3
CCI IDS

09719844

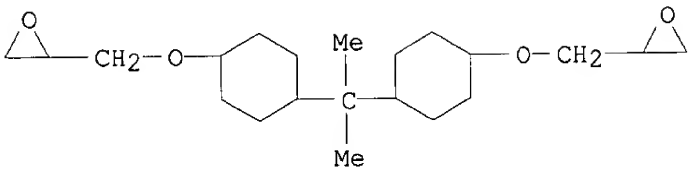
CDES 8:ID



D1—Me

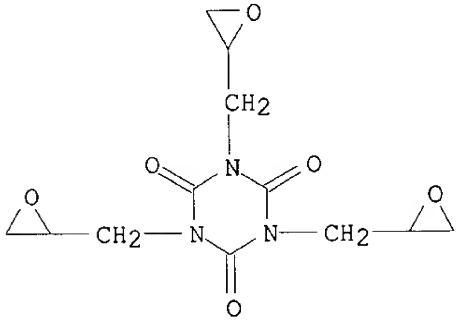
CM 2

CRN 13410-58-7
CMF C21 H36 O4



CM 3

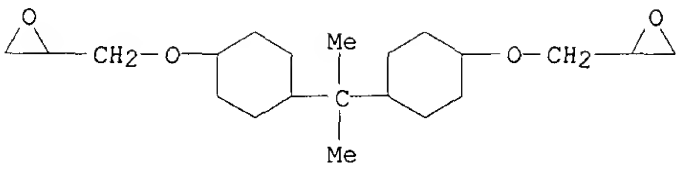
CRN 2451-62-9
CMF C12 H15 N3 O6



RN 129825-76-9 CAPLUS
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with N-(2-aminoethyl)-N'-[2-[(2-aminoethyl)amino]ethyl]-1,2-ethanediamine and 2,2'-[(1-methylethylidene)bis(4,1-cyclohexanediyloxymethylene)]bis[oxirane] (9CI) (CA INDEX NAME)

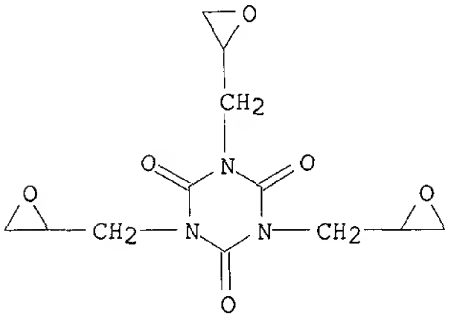
CM 1

CRN 13410-58-7
CMF C21 H36 O4



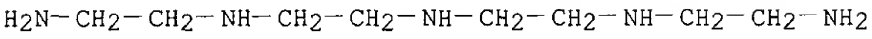
CM 2

CRN 2451-62-9
CMF C12 H15 N3 O6



CM 3

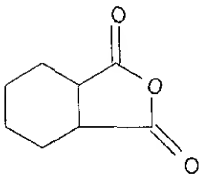
CRN 112-57-2
CMF C8 H23 N5



RN 129825-77-0 CAPLUS
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with hexahydromethyl-1,3-isobenzofurandione (9CI) (CA INDEX NAME)

CM 1

CRN 25550-51-0
CMF C9 H12 O3
CCI IDS
CDES 8:ID

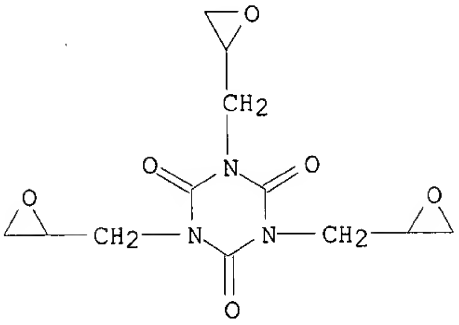


D1—Me

09719844

CM 2

CRN 2451-62-9
CMF C12 H15 N3 O6



=>

---Logging off of STN---

=>
Executing the logoff script...

=> LOG Y

COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	57.12	197.61

DISCOUNT AMOUNTS (FOR QUALIFYING ACCOUNTS)	SINCE FILE ENTRY	TOTAL SESSION
CA SUBSCRIBER PRICE	-6.82	-6.82

STN INTERNATIONAL LOGOFF AT 18:28:39 ON 13 MAY 2002

09719844

Welcome to STN International! Enter x:x

LOGINID:ssspta1712mxf

PASSWORD:
TERMINAL (ENTER 1, 2, 3, OR ?):2

* * * * * * * * * * Welcome to STN International * * * * * * * * * *

NEWS		Web Page URLs for STN Seminar Schedule - N. America
NEWS 2	Jan 25	BLAST(R) searching in REGISTRY available in STN on the Web
NEWS 3	Jan 29	FSTA has been reloaded and moves to weekly updates
NEWS 4	Feb 01	DKILIT now produced by FIZ Karlsruhe and has a new update frequency
NEWS 5	Feb 19	Access via Tymnet and SprintNet Eliminated Effective 3/31/02
NEWS 6	Mar 08	Gene Names now available in BIOSIS
NEWS 7	Mar 22	TOXLIT no longer available
NEWS 8	Mar 22	TRCTHERMO no longer available
NEWS 9	Mar 28	US Provisional Priorities searched with P in CA/CAplus and USPATFULL
NEWS 10	Mar 28	LIPINSKI/CALC added for property searching in REGISTRY
NEWS 11	Apr 02	PAPERCHEM no longer available on STN. Use PAPERCHEM2 instead.
NEWS 12	Apr 08	"Ask CAS" for self-help around the clock
NEWS 13	Apr 09	BEILSTEIN: Reload and Implementation of a New Subject Area
NEWS 14	Apr 09	ZDB will be removed from STN
NEWS 15	Apr 19	US Patent Applications available in IFICDB, IFIPAT, and IFIUDB
NEWS 16	Apr 22	Records from IP.com available in CAPLUS, HCAPLUS, and ZCAPLUS
NEWS 17	Apr 22	BIOSIS Gene Names now available in TOXCENTER
NEWS 18	Apr 22	Federal Research in Progress (FEDRIP) now available

NEWS EXPRESS	February 1 CURRENT WINDOWS VERSION IS V6.0d, CURRENT MACINTOSH VERSION IS V6.0a(ENG) AND V6.0Ja(JP), AND CURRENT DISCOVER FILE IS DATED 05 FEBRUARY 2002
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FILE 'HOME' ENTERED AT 18:39:20 ON 13 MAY 2002

=> file registry

COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	0.21	0.21

09719844

FILE 'REGISTRY' ENTERED AT 18:39:52 ON 13 MAY 2002
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STRUCTURE FILE UPDATES: 12 MAY 2002 HIGHEST RN 414856-11-4
DICTIONARY FILE UPDATES: 12 MAY 2002 HIGHEST RN 414856-11-4

TSCA INFORMATION NOW CURRENT THROUGH July 7, 2001

Please note that search-term pricing does apply when conducting SmartSELECT searches.

Crossover limits have been increased. See HELP CROSSOVER for details.

Calculated physical property data is now available. See HELP PROPERTIES for more information. See STNote 27, Searching Properties in the CAS Registry File, for complete details:
http://www.cas.org/ONLINE/STN/STNOTES/stnotes27.pdf

=>
Uploading 09543628b.str

L1 STRUCTURE UPLOADED

=> s full l1
FULL SEARCH INITIATED 18:40:50 FILE 'REGISTRY'
FULL SCREEN SEARCH COMPLETED - 3372 TO ITERATE

100.0% PROCESSED 3372 ITERATIONS 1206 ANSWERS
SEARCH TIME: 00.00.01

L2 1206 SEA SSS FUL L1

=> file caplus

COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	140.66	140.87

FILE 'CAPLUS' ENTERED AT 18:40:54 ON 13 MAY 2002
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FILE COVERS 1907 - 13 May 2002 VOL 136 ISS 20
FILE LAST UPDATED: 10 May 2002 (20020510/ED)

This file contains CAS Registry Numbers for easy and accurate substance identification.

CAS roles have been modified effective December 16, 2001. Please check your SDI profiles to see if they need to be revised. For information on CAS roles, enter HELP ROLES at an arrow prompt or use the CAS Roles thesaurus (/RL field) in this file.

```
=> s l2 and electronic and (adhesive or adhesion)
          1372 L2
        363585 ELECTRONIC
         21498 ELECTRONICS
        378840 ELECTRONIC
                 (ELECTRONIC OR ELECTRONICS)
        141668 ADHESIVE
         92659 ADHESIVES
        160378 ADHESIVE
                 (ADHESIVE OR ADHESIVES)
        200551 ADHESION
          2593 ADHESIONS
        201407 ADHESION
                 (ADHESION OR ADHESIONS)
L3            0 L2 AND ELECTRONIC AND (ADHESIVE OR ADHESION)

=> s l2 and electronic
          1372 L2
        363585 ELECTRONIC
         21498 ELECTRONICS
        378840 ELECTRONIC
                 (ELECTRONIC OR ELECTRONICS)
L4            6 L2 AND ELECTRONIC

=> d ibib abs hitstr 1

L4   ANSWER 1 OF 6  CAPLUS  COPYRIGHT 2002 ACS
ACCESSION NUMBER:         2001:136798  CAPLUS
DOCUMENT NUMBER:          134:194125
TITLE:                    Meltable resins based on unsaturated polyesters and
                          their use
INVENTOR(S):              Lienert, Klaus-Wilhelm; Hegemann, Guenter; Eichhorst,
                          Manfred
PATENT ASSIGNEE(S):       Schenectady International Inc., USA
SOURCE:                   Ger. Offen., 12 pp.
                          CODEN: GWXXBX
DOCUMENT TYPE:            Patent
LANGUAGE:                 German
FAMILY ACC. NUM. COUNT:   1
PATENT INFORMATION:

     PATENT NO.        KIND  DATE           APPLICATION NO.  DATE
     ---------------   ----  --------       ---------------  --------
     DE 19939759        A1   20010222       DE 1999-19939759 19990821
     WO 2001014473      A1   20010301       WO 2000-EP7381   20000731
         W:  KR, US
         RW: AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL,
             PT, SE
PRIORITY APPLN. INFO.:                    DE 1999-19939759 A  19990821
AB   Compns. with low m.p., good storage stability in the solid state, and fast
     curability in the melt state contain (A) .gtoreq.1 solid unsatd. polyester
     and (B) .gtoreq.1 oligomer and(or) polymer having terminal and(or) side
     propenyl, isopropenyl and(or) (meth)acrylate ester groups as crosslinkers
     for the unsatd. polyesters.  These compns. are useful in the manuf. of
     coatings and cast moldings, and as impregnants for in the manuf. of
     electronic parts.  A typical (B) was manufd. by heating a mixt.
     contg. adipic acid 1753.7, isoprenol 478.6, hydrogenated bisphenol A
```

368.4, THEIC 261.7, PhMe 400, and Sn catalyst 6 g 3 h at 130.degree. under N, heating the mixt. to 190.degree. in 2 h, and heating 4 h at 190.degree..

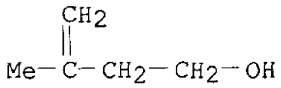
IT **327969-22-2P**
RL: IMF (Industrial manufacture); MOA (Modifier or additive use); PEP (Physical, engineering or chemical process); PREP (Preparation); PROC (Process); USES (Uses)
(crosslinker; meltable resins based on unsatd. polyesters and oligomers or polymers having isoprenyl, propenyl, or (meth)acrylate groups as crosslinkers)

RN 327969-22-2 CAPLUS

CN Hexanedioic acid, polymer with 4,4'-(1-methylethylidene)bis[cyclohexanol] and 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione, 3-methyl-3-butenyl ester (9CI) (CA INDEX NAME)

CM 1

CRN 763-32-6
CMF C5 H10 O

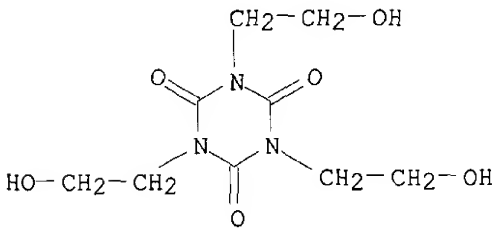


CM 2

CRN 327969-21-1
CMF (C15 H28 O2 . C9 H15 N3 O6 . C6 H10 O4)x
CCI PMS

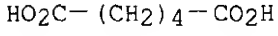
CM 3

CRN 839-90-7
CMF C9 H15 N3 O6



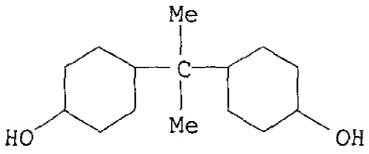
CM 4

CRN 124-04-9
CMF C6 H10 O4



CM 5

CRN 80-04-6
CMF C15 H28 O2

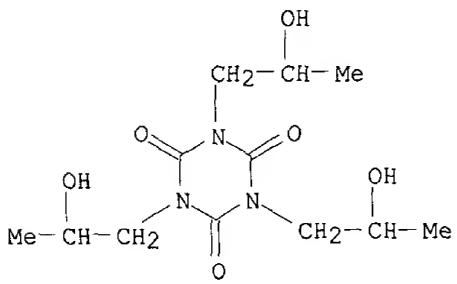


=> d ibib abs hitstr 2

L4 ANSWER 2 OF 6 CAPLUS COPYRIGHT 2002 ACS
ACCESSION NUMBER: 1998:314230 CAPLUS
DOCUMENT NUMBER: 128:325252
TITLE: Soldering flux containing tris(2-hydroxyproplyl)isocyanurate
INVENTOR(S): Ikeda, Hisao; Oosawa, Kenichi; Koda, Toshinari
PATENT ASSIGNEE(S): Nissan Chemical Industries, Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 10128577	A2	19980519	JP 1996-280606	19961023

AB A soldering flux contains tris(2-hydroxyproplyl)isocyanurate for improved reliability of soldered joints in **electronics**. A paste solder contains the flux and a metal powder having a m.p. of 40-450.degree..
IT **4885-66-9**, Tris(2-hydroxypropyl)isocyanurate
RL: MOA (Modifier or additive use); USES (Uses)
(soldering flux contg. tris(2-hydroxyproplyl)isocyanurate)
RN 4885-66-9 CAPLUS
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(2-hydroxypropyl)- (9CI) (CA INDEX NAME)



=> d ibib abs hitstr 3

L4 ANSWER 3 OF 6 CAPLUS COPYRIGHT 2002 ACS
ACCESSION NUMBER: 1987:167274 CAPLUS
DOCUMENT NUMBER: 106:167274

09719844

TITLE: UV-cured flexible polyester-monoacrylate protective thermistor coatings having good edge coverage and a method of coating
INVENTOR(S): Hudock, John S.
PATENT ASSIGNEE(S): Westinghouse Electric Corp., USA
SOURCE: U.S., 7 pp.
CODEN: USXXAM
DOCUMENT TYPE: Patent
LANGUAGE: English
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
US 4623559	A	19861118	US 1985-755134	19850712

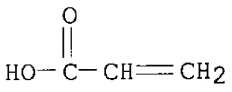
AB **Electronic** components such as thermistors are coated with a liq. resin compn. contg. a polyester-methacrylate and a photoinitiator. The components are axially rotated to control dripping and subjected to UV radiation to cure the resin. Coatings displaying good crack resistance, flexibility, thermal stability, and edge coverage were obtained.

IT **107721-32-4**
RL: USES (Uses)
(UV-curable coating compn. contg., for **electronic** components)

RN 107721-32-4 CAPLUS
CN 1,4-Benzenedicarboxylic acid, polymer with 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione, 2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 79-10-7
CMF C3 H4 O2

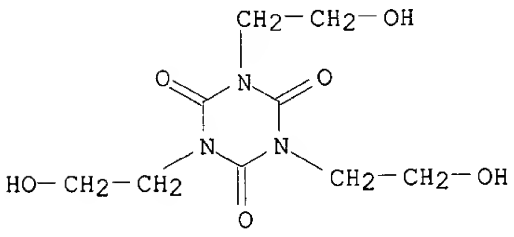


CM 2

CRN 26337-62-2
CMF (C9 H15 N3 O6 . C8 H6 O4)x
CCI PMS

CM 3

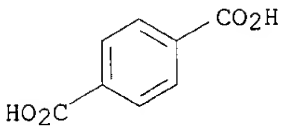
CRN 839-90-7
CMF C9 H15 N3 O6



09719844

CM 4

CRN 100-21-0
CMF C8 H6 O4

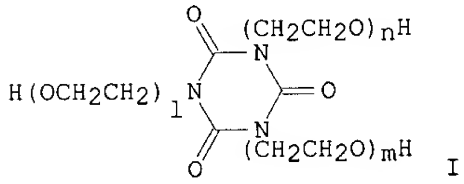


=> d ibib abs hitstr 4

L4 ANSWER 4 OF 6 CAPLUS COPYRIGHT 2002 ACS
ACCESSION NUMBER: 1984:552919 CAPLUS
DOCUMENT NUMBER: 101:152919
TITLE: Thermosetting resin compositions
PATENT ASSIGNEE(S): Hitachi Chemical Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 8 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 59080416	A2	19840509	JP 1982-191149	19821029
JP 60017447	B4	19850502		

GI



I

AB Thermosetting resin compns. are composed of (1) a bisphenol epoxy resin unsatd. acid ester, (2) an isocyanurate obtained by esterification of I (l, m, n = 1, 2) with a monobasic unsatd. acid or its lower alkyl ester, and (3) other monomer(s) if necessary. Optionally, a polyisocyanate is also added to the compn. The compns. exhibit good hardening properties and workability, and give cured products having good heat resistance, water resistance, and high mech. strength. The compns. are esp. useful in fabrication and coating of **electronic** devices. Thus, an ester prepd. from methacrylic acid 2.00, Epikote 828 0.40, and Epikote 1001 0.60 mol was mixed 70:30 with styrene, while 70 parts acrylic acid ester of I (l = m = n = 1) was dissolved in 30 parts styrene. The 2 solns. in 9:1 ratio were then mixed with 1% benzoyl peroxide and formed into a sheet (cured at 80.degree., with after-cure treatment at 120.degree.), which showed bending strength 13.0 kg/mm2 and thermal deformation temp. 120.degree. (JIS K 6911).

IT **88403-03-6 88403-04-7**

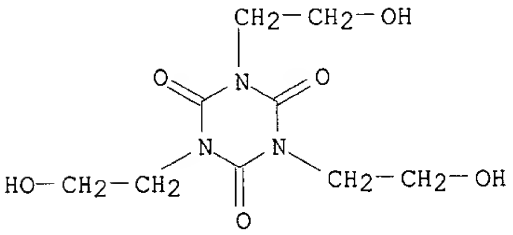
RL: MOA (Modifier or additive use); USES (Uses)
(crosslinking agents, for epoxy resin methacrylates)

RN 88403-03-6 CAPLUS

CN 2-Propenoic acid, ester with 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

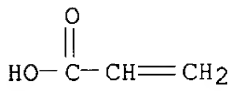
CM 1

CRN 839-90-7
CMF C9 H15 N3 O6



CM 2

CRN 79-10-7
CMF C3 H4 O2

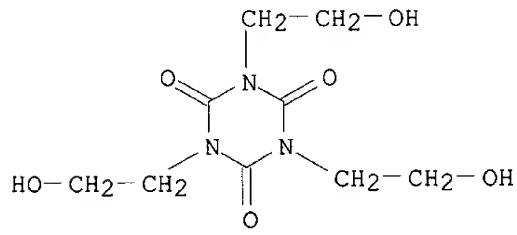


RN 88403-04-7 CAPLUS

CN 2-Propenoic acid, 2-methyl-, ester with 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

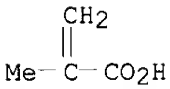
CM 1

CRN 839-90-7
CMF C9 H15 N3 O6



CM 2

CRN 79-41-4
CMF C4 H6 O2



=> d ibib abs hitstr 5

L4 ANSWER 5 OF 6 CAPLUS COPYRIGHT 2002 ACS
ACCESSION NUMBER: 1981:463137 CAPLUS
DOCUMENT NUMBER: 95:63137
TITLE: **Electronic** insulators
PATENT ASSIGNEE(S): Hitachi Chemical Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 5 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 56013607	A2	19810210	JP 1979-89656	19790713
JP 57033643	B4	19820719		

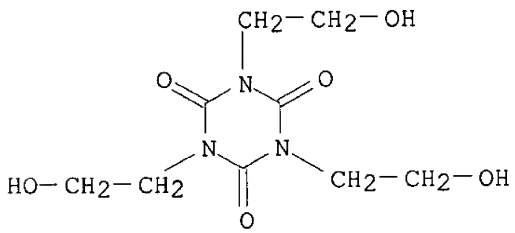
AB An elec. insulator resin compn. comprises the reaction product of a polybasic carboxylic acid or its deriv. (.gtoreq.50 equiv % of total carboxyl groups from terephthalic or isophthalic acid or their dialkyl esters) with a dihydric and a polyhydric alc. (functionality .gtoreq.3) and .apprx.5-30% (on reaction product) of a polyamide resin, which are heated until the mixt. remains transparent and homogeneous at room temp. Thus, ethylene glycol 119, glycerol 78, di-Me terephthalate 506, and Pb(OAc)2 0.71 g were heated at 150-240.degree.. To a soln. of the reaction product (155 g) in 1313 g cresol, 27 g nylon 12 [24937-16-4] (Daiamide L-1640) was added, and the mixt. was heated at 130.degree. for 3 h, at 160.degree. for .apprx.8 h [after addn. of 11 g Ti(OBu)4], and at 160.degree. for .apprx.2 h until the soln. remained clear at room temp. After addn. of 16 g Ti(OBu)4 and 9 g Zn naphthenate, the soln. remained homogeneous and transparent for 20 days at room temp.

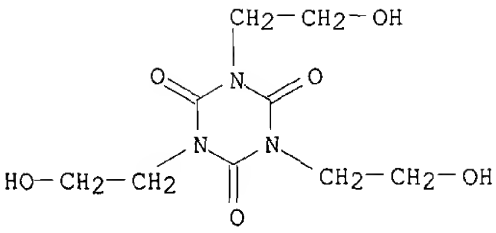
IT **31045-37-1**
RL: USES (Uses)
(elec. insulators, contg. polyamides, room temp. stability of solns. of)

RN 31045-37-1 CAPLUS
CN 1,4-Benzenedicarboxylic acid, dimethyl ester, polymer with 1,2-ethanediol and 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

CM 1

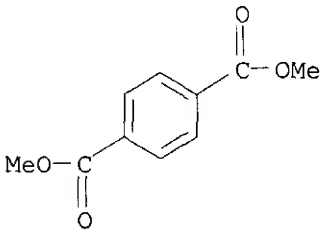
CRN 839-90-7
CMF C9 H15 N3 O6





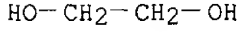
CM 2

CRN 120-61-6
CMF C10 H10 O4



CM 3

CRN 107-21-1
CMF C2 H6 O2



=> d ibib abs hitstr 6

L4 ANSWER 6 OF 6 CAPLUS COPYRIGHT 2002 ACS
ACCESSION NUMBER: 1976:495178 CAPLUS
DOCUMENT NUMBER: 85:95178
TITLE: Hardenable, heat-resistant unsaturated polyester resins, especially for use in the **electronics** industry
INVENTOR(S): Janssen, Harald; Hegemann, Guenther
PATENT ASSIGNEE(S): Beck, Dr., und Co. A.-G., Ger.
SOURCE: Ger. Offen., 12 pp.
CODEN: GWXXBX
DOCUMENT TYPE: Patent
LANGUAGE: German
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
DE 2460768	A1	19760701	DE 1974-2460768	19741221
DE 2460768	B2	19810409		
DE 2460768	C3	19820408		
ES 442941	A1	19770801	ES 1975-442941	19751125

NL 7514640	A	19760623	NL 1975-14640	19751216
NL 169598	B	19820301		
NL 169598	C	19820802		
FR 2295051	A1	19760716	FR 1975-38899	19751218
FR 2295051	B1	19800523		
SE 7514478	A	19760622	SE 1975-14478	19751219
SE 417832	B	19810413		
SE 417832	C	19810730		
JP 51089592	A2	19760805	JP 1975-150753	19751219
JP 55046405	B4	19801122		

PRIORITY APPLN. INFO.: DE 1974-2460768 19741221

AB The polyester resins were prepd. from tetrahydrophthalic anhydride (I), H2NCH2CH2OH, maleic anhydride (II), neopentyl glycol (III), tris(hydroxyethyl) isocyanurate (IV), or tris(2-carboxyethyl) isocyanurate, and, in one case, Ampol 1022 (dimerized fatty acids). Styrene solns. of the resins have a satisfactory pot life. Thus, 550 g I and 221.6 g H2NCH2CH2OH were heated <130.degree., freed of water in vacuo, mixed with II 476, III 380, Empol 1022 1092, IV 316.8, and hydroquinone 0.4 g, and heated at .ltoreq.210.degree. to give a product with acid no. <25, and the resin was mixed with styrene and 2% Me Et ketone peroxide to prepare a resin with gel time 15 min. The hardened resin was heated 7 days at 250.degree. with wt. loss 6.9%.

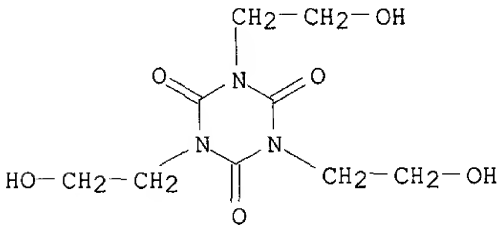
IT **60262-73-9 60262-74-0**
RL: USES (Uses)
(styrene-crosslinked, heat-resistant, elec. insulators)

RN 60262-73-9 CAPLUS

CN 9,12-Octadecadienoic acid (9Z,12Z)-, dimer, polymer with 2-aminoethanol, 2,2-dimethyl-1,3-propanediol, 2,5-furandione, 3a,4,7,7a-tetrahydro-1,3-isobenzofurandione and 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

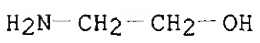
CM 1

CRN 839-90-7
CMF C9 H15 N3 O6



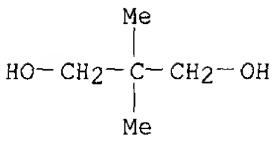
CM 2

CRN 141-43-5
CMF C2 H7 N O



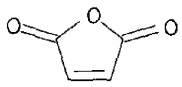
CM 3

CRN 126-30-7
CMF C5 H12 O2



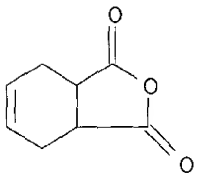
CM 4

CRN 108-31-6
CMF C4 H2 O3



CM 5

CRN 85-43-8
CMF C8 H8 O3



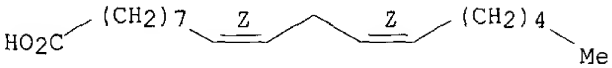
CM 6

CRN 6144-28-1
CMF (C18 H32 O2)2
CCI PMS

CM 7

CRN 60-33-3
CMF C18 H32 O2
CDES 2:Z,Z

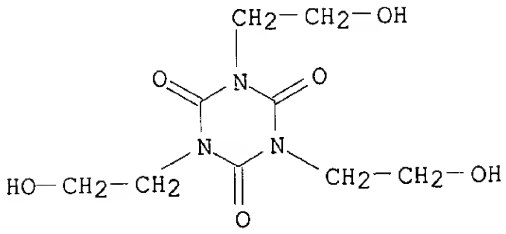
Double bond geometry as shown.



RN 60262-74-0 CAPLUS
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(2-hydroxyethyl)-, polymer with 2-aminoethanol, 2,2-dimethyl-1,3-propanediol, 2,5-furandione and 3a,4,7,7a-tetrahydro-1,3-isobenzofurandione (9CI) (CA INDEX NAME)

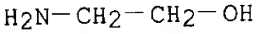
CM 1

CRN 839-90-7
CMF C9 H15 N3 O6



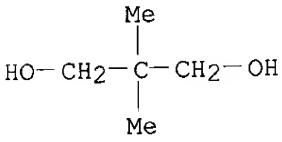
CM 2

CRN 141-43-5
CMF C2 H7 N O



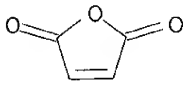
CM 3

CRN 126-30-7
CMF C5 H12 O2



CM 4

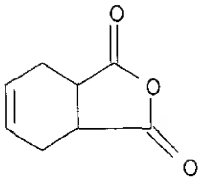
CRN 108-31-6
CMF C4 H2 O3



CM 5

CRN 85-43-8
CMF C8 H8 O3

09719844



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---Logging off of STN---

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Executing the logoff script...

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COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	36.01	176.88

DISCOUNT AMOUNTS (FOR QUALIFYING ACCOUNTS)	SINCE FILE ENTRY	TOTAL SESSION
CA SUBSCRIBER PRICE	-3.72	-3.72

STN INTERNATIONAL LOGOFF AT 18:45:56 ON 13 MAY 2002